

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI17 1.5mm wire to board Connector	SPEC.NO.: SPCI097B
REVISIONS	ECNT120150		PAGE: 1/4

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: CI1703M1VR0-NH (Halogen-Free)

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Sun VERIFIED : Michelle .

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI17 1.5mm wire to board Connector	SPEC.NO.: SPCI097B
REVISIONS	ECNT120150		PAGE: 2/4

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A (AWG#28), 250V AC/DC
7.2	Contact resistance	Dry circuit of DC 20mV max. , 100mA max., Wire resistance shall be removed from the measured value.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1500 V 1 minute between adjacent terminal	No Breakdown Current leakage<5mA
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push Pin from insulator base at speed 25± 3 mm per minute	More than 0.7 kgf

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30° C Max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	105± 2° C, 96 hours	No damage
9.4	Humidity	60± 2° C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: 40 mΩ Max. Insulation resistance: 100MΩ Min. Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1) -40 ⁺⁰ / ₋₃ ° C , 30 min. (2) Room temp. 10-15 min. (3) 105 ⁺³ / ₋₀ ° C , 30 min. (4) Room temp. 10-15 min. Total cycle: 5 cycle	Appearance: No damage Contact resistance: 20 mΩ Max.



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI17 1.5mm wire to board Connector	SPEC.NO.: SPCI097B
REVISIONS	ECNT120150		PAGE: 3/4

	ITEM	TEST CONDITION	REQUIREMENT
9.6	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: $40\text{ m}\Omega$ Max.
9.7	Solder ability	Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area
9.8	Resistance to soldering heat	Refer Reflow temperature profile(11.1)	No damage

10. AMBIENT TEMPERATURE RANGE: -25 to + 130 °C

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI17 1.5mm wire to board Connector	SPEC.NO.: SPCI097B
REVISIONS	ECNT120150		PAGE: 4/4

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Paste

